TAI-TECH KBM01-210800541 P2.

Ferrite Chip Inductor(Lead Free)

FCI2012F-5R6K

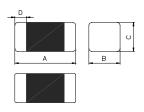
Certificate

Green Partner

1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3. S.M.T. type.
- 4. Suitable for reflow soldering.
- 5. Shapes and dimensions follow E.I.A. spec.
- 6. Available in various sizes.
- 7. Excellent solder ability and heat resistance.
- 8. High reliability.
- 9. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 10. Operating Temperature: -55~+105 $^{\circ}$ C (Including self-temperature rise)

2. Dimensions



Chip Size						
A	2.00±0.20					
В	1.25±0.20					
С	1.25±0.20					
D	0.50±0.30					

3. Part Numbering

FCI 2012 F - 5R6 K A B C D E

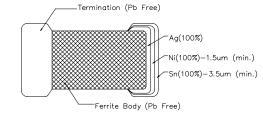
A: Series

B: Dimension

C: Material Lead Free Material
D: Inductance 5R6=5.6uH

E: Inductance Tolerance K=±10%, L=±15%, M=±20%

LxW



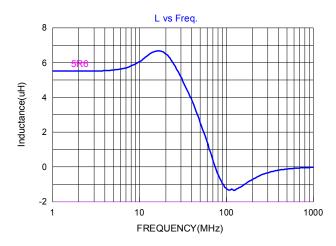
4. Specification

Tai-Tech	Induct	ance(<mark>uH</mark>)		Q Rated Current D		DCR	SRF
Part Number	Tolerance	Test Frequency (Hz)	min.	Test Frequency (MHz)	(mA) max.	(Ω) max.	(MHz) min.
FCI2012F-5R6K	5.6±10%	60mV / 4M	45	4	15	0.90	32

Units: mm

- Rated current: based on temperature rise test
- In compliance with EIA 595

Inductance-Frequency Characteristics



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TAI-TECH KBM01-210800541 P3.

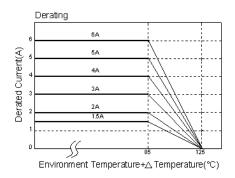
5. Reliability and Test Condition

Item		Pe	rfor	mance			Те	st Cond	dition	
Series No.	FCI	FHI		FCH	HCI					
Operating Temperature				-105℃ emperature rise)		-				
Transportation Storage Temperature				-105℃ oard)		For long storage conditions, please see t Application Notice				see the
Inductance (Ls)						Agilent4291 Agilent E4991				
Q Factor	Refer to stand	efer to standard electrical characteristics list								
DC Resistance						Agilent 4				
Rated Current						DC Pow Over Ra some ris	ted Curr		ements, the	ere will be
Temperature Rise Test	Rated Current < 1. Rated Current ≧					2. Tempe			current. by digital si	urface
Life test		no damage. ithin±15%of initial va thin±10%of initial va				times.(II Reflow F Tempera Applied of Duration Measure for 24±2 Precond	PC/JED Profiles) ature: 10 current: : 1000± ed at ro hrs. itioning:	EC J-STD 5±2℃ rated curr 12hrs. om tempe Run thro	erature afte	er placing
Load Humidity		exceed the specifical £15% of initial value		value. shall not exceed the	specification value	Reflow F Humidity Tempera Duration ent In	Profiles) r: 85±2% ture: 85 :1000hr ductanced at ro	6R.H. ±2°⊜. sMin.Bead e: with	d:with100% 10% rated erature afte	ratedcurr I current
Thermal shock	Inductance: wi	ithin±15%of initial va thin±10%of initial va exceed the specifical	alue. ition v	value. shall not exceed the	specification value	times.(II Reflow F Condition Step1: -5 Step2: 1 Step3: 1 Number	PC/JED Profiles) n for 1 c 55±2°C 05±2°C 05±2°C of cycle ed at ro	eycle 30±5 ≤0.5 30±5mi s: 500	imin	ssification
Vibration	Inductance : v Q : Shall not e	vithin±15% of initial vithin±10% of initial vexceed the specifical	value tion v	e	specification value	times.(II Reflow F Oscillation for 20 mi Equipment Total Am	PC/JED Profiles) on Freq inutes ent : Vi plitude:	EC J-STD juency: 10 bration cho 10g 2 hours(20	ugh IR refi I-020E Clas DHz ~ 2KH ecker O minutes,	ssification z ~ 10Hz
Bending	Inductance : v Q : Shall not e	vithin±10% of initial vithin±10% of initial vexceed the specifical	value tion v	e	specification value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805inch(2012mm):40x100x1.2mm <0805inch(2012mm):40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805inch(2012mm):0.8mm Duration of 10 sec for a min.				
	Appearance :	No damage.	valu	a.		Test co	ndition Peak Value	Normal duration	Wave form	Velocity change
Shock	Inductance : v Q : Shall not e	vithin±10% of initial vexceed the specifical	value tion v	e	specification value	SMD	(g's) 50	(D) (ms)	Half-sine	(Vi)ft/sec 11.3
Insulation Resistance	IR>1GΩ					Chip Ind	uctor Or	nly		11.3
Solderability		o of the terminal elec	ctrode	e should be covered	with solder.	Test Voltage:100±10%V for 30Sec. a.Method B, 4 hrs @155°C dry heat @235°C±5°C Test time:5 +0/-0.5 seconds. b. Method D category 3. (steam aging 8hours ± 15 min)@ 260°C±5°C Test time: 30 +0/-0.5 seconds.				

Item	Performance	Test Condition
		Number of heat cycles: 1
Resistance to Soldering	Appearance : No damage. Impedance : within±15% of initial value	Temperature (°C) Time (s) Temperature ramp/immersion and emersion rate
Heat	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	260 ±5 (solder temp) 10 ±1 25mm/s ±6 mm/s
		Depth: completely cover the termination
Terminal strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Component mounted on a PCB apply a force >0805inch(2012mm):1kg <0805inch(2012mm):0.5kg to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.

**Derating Curve

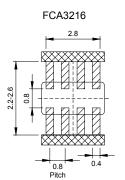
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over $85^{\circ}\mathbb{C}$, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



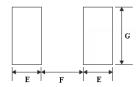
6. Soldering and Mounting

6-1. Recommended PC Board Pattern

		Land Patterns For Reflow Soldering						
Series	Туре	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
FCB	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
HCB	2012	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.05	1.00	1.45
GHB	2012	2.0±0.20	<mark>1.25±0.20</mark>	1.25±0.20	<mark>0.50±0.30</mark>	1.05	<mark>1.00</mark>	1.45
<mark>FCI</mark>	3216	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	1.05	2.20	1.80
FHI	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70
FCH	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80
HCI	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40



Land
Solder Resist



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

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6-2.1 IR Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip1.0mm tip diameter (max)
- · Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.

Fig.1 IR Soldering Reflow

• 350°C tip temperature (max)

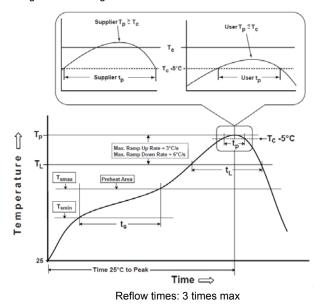
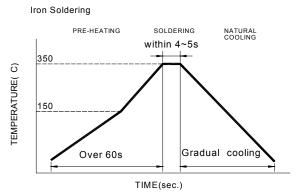


Fig.2 Iron soldering temperature profiles



Iron Soldering times: 1 times max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
$\label{eq:continuous_series} \begin{split} & - \text{Temperature Min}(T_{\text{smin}}) \\ & - \text{Temperature Max}(T_{\text{smax}}) \\ & - \text{Time}(t_{\text{s}}) \text{from}(T_{\text{smin}} \text{ to } T_{\text{smax}}) \end{split}$	150℃ 200℃ 60-120seconds
Ramp-up rate(T_L to T_p)	3°C/second max.
$\label{eq:Liquidus} \begin{array}{c} \text{Liquidus temperature}(T_L) \\ \text{Time}(t_L) \text{maintained above } T_L \end{array}$	217°C 60-150 seconds
Classification temperature(T _c)	See Table (1.2)
$\label{eq:total_final} \mbox{Time}(t_p) \mbox{ at Tc-} \mbox{ 5^{\circ}\!$	< 30 seconds
Ramp-down rate(T _p to T _L)	6°C /second max.
Time 25℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, Tc: the classification temperature.

For user (customer) ${\bf Tp}$ should be equal to or less than ${\bf Tc.}$

Table (1.2) Package Thickness/Volume and Classification Temperature (Tc)

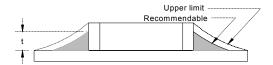
	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
	<1.6mm	260°C	260°C	260°C
PB-Free Assembly	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E •

6-2.3 Solder Volume:

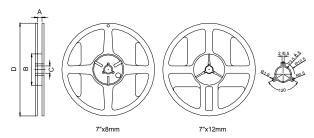
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



7.Packaging Information

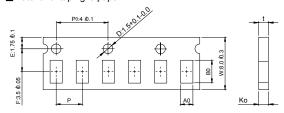
7-1. Reel Dimension



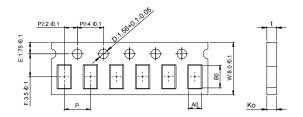
	Туре	A(mm)	B(mm)	C(mm)	D(mm)
	<mark>7"x8mm</mark>	9.0±0.5	<mark>60±2</mark>	<mark>13.5±0.5</mark>	<mark>178±2</mark>
7"x12mm		13.5±0.5	60±2	13.5±0.5	178±2

7-2.1 Tape Dimension / 8mm

■Material of taping is paper

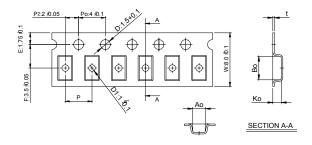


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03



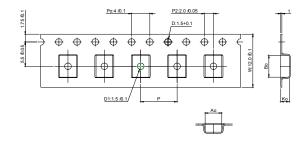
Ī	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
	160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
	201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
<mark>201212</mark>	<mark>2.10±0.10</mark>	<mark>1.28±0.10</mark>	<mark>1.28±0.10</mark>	<mark>4.0±0.10</mark>	0.22±0.05	<mark>1.0±0.10</mark>
321611	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

7-2.2 Tape Dimension / 12mm



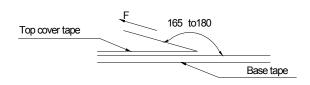
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

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7-3. Packaging Quantity

Chip Size	453215	451616	322513	321611	321609	<mark>201212</mark>	201209	160808	100505
Chip / Reel	1000	2000	2500	3000	3000	<mark>2000</mark>	4000	4000	10000
Inner box	4000	8000	12500	15000	15000	<mark>10000</mark>	20000	20000	50000
Middle box	20000	40000	62500	75000	75000	<mark>50000</mark>	100000	100000	250000
Carton	40000	80000	125000	150000	150000	<mark>100000</mark>	200000	200000	500000

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

Storage Conditions(component level)

To maintain the solder ability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.





Test Report

號碼(No.): ETR20C00900

日期(Date): 10-Dec-2020

頁數(Page): 1 of 13

西北臺慶科技股份有限公司 (TAI-TECH ADVANCED ELECTRONICS CO., LTD.)

臺慶精密電子(昆山)有限公司 (TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

慶邦電子元器件 (洒洪) 有限公司 (TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

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江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 (GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

中國·江蘇省·宿遷市·泗洪縣·經濟開發區杭州路南側·建設北路東側 (THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD · ECONOMIC DEVELOPMENT ZONE · SIHONG COUNTY · SUQIANCITY · JIANGSU PROVINCE · P,R · CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Name)

: FERRITE CHIP BEAD . FERRITE CHIP INDUCTOR . ARRAY . MCF . MCM .

YMV · APM SERIES

樣品型號(Style/Item No.)

FERRITE CHIP BEAD . FERRITE CHIP INDUCTOR . ARRAY . MCF . MCM .

YMV - APM SERIES

收件日(Sample Receiving Date)

03-Dec-2020

測試期間(Testing Period)

03-Dec-2020 to 10-Dec-2020

測試需求(Test Requested)

依據客戶要求進行測試‧測試項目請參閱測試結果表格。 (Testing item(s) is/are specified by client. Please refer to result table for testing item(s).)

測試結果(Test Results)

請參閱下一頁 (Please refer to following pages.)





PIN CODE: A4F57BI

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Test Report

號碼(No.): ETR20C00900

日期(Date): 10-Dec-2020

頁數(Page): 2 of 13

西北臺慶科技股份有限公司 (TAI-TECH ADVANCED ELECTRONICS CO., LTD.)

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測試部位敘述 (Test Part Description)

No 1

整體混測 (MIXED ALL PARTS)

測試結果 (Test Results)

• 測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
鎘 (Cd) (Cadmium (Cd)) (CAS No.: 7440- 43-9)	参考IEC 62321-5: 2013・以感應耦合電漿發射光 譜儀分析・(With reference to IEC 62321-5:	mg/kg	2	n.d.
鉛 (Pb) (Lead (Pb)) (CAS No.: 7439-92-1)	2013, analysis was performed by ICP-OES.)	mg/kg	2	n.d.
汞 (Hg) (Mercury (Hg)) (CAS No.: 7439- 97-6)	参考IEC 62321-4: 2013+ AMD1: 2017・以感應耦合電漿發射光譜儀分析。(With reference to IEC 62321-4: 2013+ AMD1: 2017, analysis was performed by ICP-OES.)	mg/kg	2	n.d.
六價鉻 Cr(VI) (Hexavalent Chromium Cr(VI)) (CAS No.: 18540-29-9)	参考IEC 62321-7-2: 2017 · 以紫外光-可見光分光 光度計分析 · (With reference to IEC 62321-7-2: 2017, analysis was performed by UV-VIS.)	mg/kg	8	n.d.
一溴聯苯 (Monobromobiphenyl)		mg/kg	5	n.d.
二溴聯苯 (Dibromobiphenyl)		mg/kg	5	n.d.
三溴聯苯 (Tribromobiphenyl)		mg/kg	5	n.d.
四溴聯苯 (Tetrabromobiphenyl)		mg/kg	5	n.d.
五溴聯苯 (Pentabromobiphenyl)	参考IEC 62321-6: 2015 · 以氣相屬析儀/質譜儀分	mg/kg	5	n.d.
六溴聯苯 (Hexabromobiphenyl)	析・(With reference to IEC 62321-6: 2015,	mg/kg	5	n.d.
七澳聯苯 (Heptabromobiphenyl)	analysis was performed by GC/MS.)	mg/kg	5	n.d.
八溴聯苯 (Octabromobiphenyl)		mg/kg	5	n.d.
九溴聯苯 (Nonabromobiphenyl)		mg/kg	5	n.d.
十溴聯苯 (Decabromobiphenyl)		mg/kg	5	n.d.
多溴聯苯總和 (Sum of PBBs)		mg/kg		n.d.

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Test Report

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測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
一溴聯苯醚 (Monobromodiphenyl ether)		mg/kg	5	n.d.
二溴聯苯醚 (Dibromodiphenyl ether)		mg/kg	5	n.d.
三溴聯苯醚 (Tribromodiphenyl ether)		mg/kg	5	n.d.
四溴聯苯醚 (Tetrabromodiphenyl ether)		mg/kg	5	n.d.
五溴聯苯醚 (Pentabromodiphenyl ether)	参考IEC 62321-6: 2015 · 以氣相屬析儀/質譜儀分	mg/kg	5	n.d.
六溴聯苯醚 (Hexabromodiphenyl ether)	析・(With reference to IEC 62321-6: 2015,	mg/kg	5	n.d.
七溴聯苯醚 (Heptabromodiphenyl ether)	analysis was performed by GC/MS.)	mg/kg	5	n.d.
八溴聯苯醚 (Octabromodiphenyl ether)		mg/kg	5	n.d.
九溴聯苯醚 (Nonabromodiphenyl ether)		mg/kg	5	n.d.
十溴聯苯醚 (Decabromodiphenyl ether)		mg/kg	5	n.d.
多溴聯苯醚總和 (Sum of PBDEs)		mg/kg	-	n.d.
六溴環十二烷及所有主要被辨別出的異構	参考IEC 62321: 2008 · 以氣相屬析儀/質譜儀分	mg/kg	5	n.d.
物(HBCDD) (α- HBCDD, β- HBCDD, γ-	析・(With reference to IEC 62321: 2008, analysis			
HBCDD) (Hexabromocyclododecane	was performed by GC/MS.)			
(HBCDD) and all major			•	ì
diastereoisomers identified (α- HBCDD,				
β- HBCDD, γ- HBCDD)) (CAS No.:				
25637-99-4, 3194-55-6 (134237-51-7,				}
134237-50-6, 134237-52-8))				
氟 (F) (Fluorine (F)) (CAS No.: 14762-94-		mg/kg	50	n.d.
8)				
氯 (CI) (Chlorine (CI)) (CAS No.: 22537-	参考BS EN 14582: 2016・以離子屬析儀分析・	mg/kg	50	n.d.
15-1)	(With reference to BS EN 14582: 2016, analysis			
澳 (Br) (Bromine (Br)) (CAS No.: 10097-	was performed by IC.)	mg/kg	50	n.d.
32-2)				
碘 (I) (lodine (I)) (CAS No.: 14362-44-8)		mg/kg	5.0	n.d.

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測試項目 (Test Items)	測試方法 (Method)	單位 (Unit)	MDL	結果 (Result) No.1
鄰苯二甲酸丁苯甲酯 (BBP) (Butyl benzyl phthalate (BBP)) (CAS No.: 85-68-7)		mg/kg	50	n.d.
鄉苯二甲酸二丁酯 (DBP) (Dibutyl phthalate (DBP)) (CAS No.: 84-74-2)		mg/kg	50	n.d.
郷苯二甲酸二(2-乙基己基)酯 (DEHP) (Di- (2-ethylhexyl) phthalate (DEHP)) (CAS No.: 117-81-7)		mg/kg	50	n.d.
鄭苯二甲酸二異丁酯 (DIBP) (Diisobutyl phthalate (DIBP)) (CAS No.: 84-69-5)		mg/kg	50	n.d.
鄰苯二甲酸二異癸酯 (DIDP) (Diisodecyl phthalate (DIDP)) (CAS No.: 26761-40- 0, 68515-49-1)	参考IEC 62321-8: 2017・以氣相層析儀/質譜儀分析・(With reference to IEC 62321-8: 2017,	mg/kg	50	n.d.
鄰苯二甲酸二異壬酯 (DINP) (Diisononyl phthalate (DINP)) (CAS No.: 28553-12- 0, 68515-48-0)	analysis was performed by GC/MS.)	mg/kg	50	n.d.
鄰苯二甲酸二正辛酯 (DNOP) (Di-n-octyl phthalate (DNOP)) (CAS No.: 117-84-0)		mg/kg	50	n.d.
鄰苯二甲酸二正戊酯 (DNPP) (Di-n-pentyl phthalate (DNPP)) (CAS No.: 131-18-0)		mg/kg	50	n.d.
鄰苯二甲酸二正己酯 (DNHP) (Di-n-hexyl phthalate (DNHP)) (CAS No.: 84-75-3)		mg/kg	50	n.d.

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測試項目	測試方法	單位	MDL	結果
(Test Items)	(Method)	(Unit)		(Result)
				No.1
聚氯乙烯 (Polyvinyl chloride) (PVC)	参考ASTM E1252: 2013·以傅立葉轉換紅外線光	**	-	Negative
	譜儀及焰色法分析・(With reference to ASTM			
	E1252: 2013, analysis was performed by FT-IR			1
	and Flame Test.)			
銻 (Sb) (Antimony (Sb)) (CAS No.: 7440-	参考US EPA 3052: 1996 · 以感應耦合電漿發射光	mg/kg	2	n.d.
36-0)	譜儀分析・(With reference to US EPA 3052:			
	1996, analysis was performed by ICP-OES.)			
砷 (As) (Arsenic (As)) (CAS No.: 7440-	参考US EPA 3052: 1996 · 以感應耦合電漿發射光	mg/kg	2	n.d.
38-2)	譜儀分析。(With reference to US EPA 3052:			
	1996, analysis was performed by ICP-OES.)			
鈹 (Be) (Beryllium (Be)) (CAS No.: 7440-	参考US EPA 3052: 1996,以感應耦合電漿發射光	mg/kg	2	n.d.
41-7)	譜儀分析・(With reference to US EPA 3052:			1
	1996, analysis was performed by ICP-OES.)			

備註(Note):

- 1. mg/kg = ppm; 0.1wt% = 1000ppm
- 2. MDL = Method Detection Limit (方法偵測極限值)
- 3. n.d. = Not Detected (未檢出); 小於MDL / Less than MDL
- 4. "-" = Not Regulated (無規格值)
- 5. **= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)
- 7. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量。
 The sample(s) was/were analyzed on behalf of the applicant as mixing sample in one testing. The above result(s) was/were only given as the informality value.

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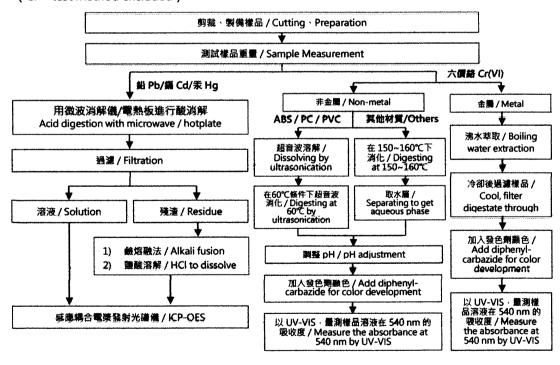
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重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr^{6+} test method excluded)



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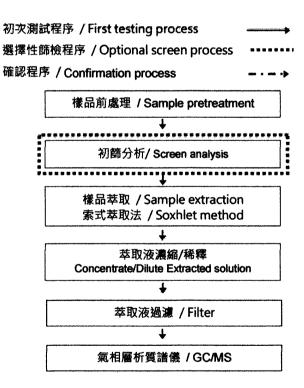
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多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBBs/PBDEs



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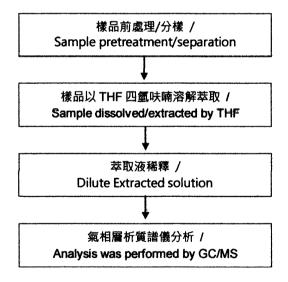
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可塑劑分析流程圖 / Analytical flow chart - Phthalate

【測試方法/Test method: IEC 62321-8】



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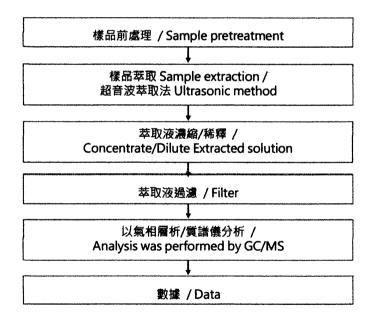
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六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD



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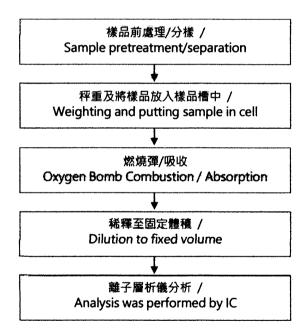
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鹵素分析流程圖 / Analytical flow chart - Halogen



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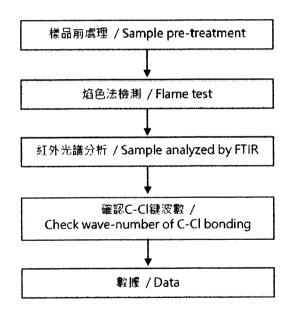
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聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC



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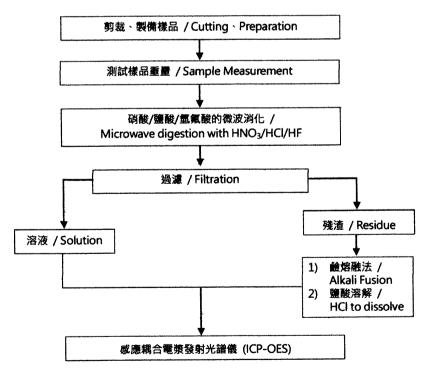
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重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件,樣品已完全溶解。

These samples were dissolved totally by pre-conditioning method according to below flow chart.

【参考方法/Reference method: US EPA 3051、US EPA 3052】



* US EPA 3051 方法未添加氫氟酸 / US EPA 3051 method does not add HF.

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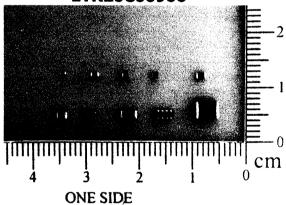
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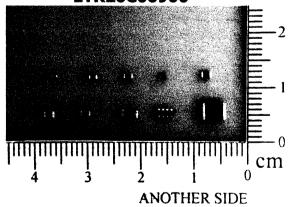
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* 照片中如有箭頭標示 · 則表示為實際檢測之樣品/部位. *
(The tested sample / part is marked by an arrow if it's shown on the photo.)

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** 報告結尾 (End of Report) **

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